

## (12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
24 June 2004 (24.06.2004)

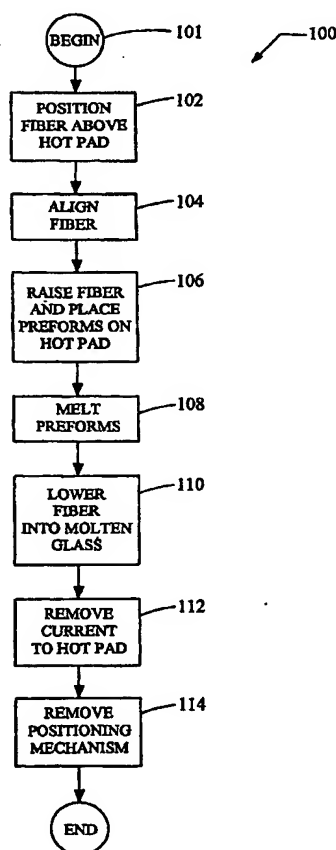
PCT

(10) International Publication Number  
**WO 2004/053537 A2**

- (51) International Patent Classification<sup>7</sup>: **G02B** Steven, L. [US/US]; 2553 Bunker Hill Road, Ann Arbor, MI 48105 (US).
- (21) International Application Number: PCT/US2003/039553 (74) Agents: CARD, John, M. et al.; Brinks Hofer gilson & Ione, P.O. Box 10087, Chicago, IL 60610 (US).
- (22) International Filing Date: 10 December 2003 (10.12.2003) (81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data: 60/432,332 10 December 2002 (10.12.2002) US
- (71) Applicant (for all designated States except US): PI-COMETRIX, INC. [US/US]; 2925 Boardwalk, Ann Arbor, MI 48104 (US).
- (84) Designated States (*regional*): ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, UA, UG, UZ, VN, YU, ZA, ZM, ZW).
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[Continued on next page]

(54) Title: PRECISION FIBER ATTACHMENT



(57) Abstract: This invention is directed to a fiber attachment including a hot pad and solder glass that attaches an optical fiber to the hot pad. The attached is formed by positioning the optical fiber over the hot pad and aligning the optical fiber. The optical fiber is then raised and solder glass preforms are positioned on the hot pad. Heat is applied to the glass preforms such that they melt. Once the preforms are melted, the optical fiber is lowered into the molten solder glass. The current is then removed and the solder glass solidifies as it cools to form an attachment between the optical fiber and the hot pad.



SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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— *of inventorship (Rule 4.17(iv)) for US only*

**Published:**

— *without international search report and to be republished upon receipt of that report*